



Printed Circuit Boards  
Interconnection Carriers

State of the Art: PCB's

Revisio

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# PRINTED CIRCUIT BOARDS

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4.11.2001

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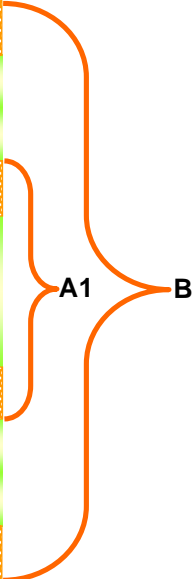
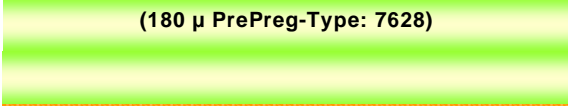


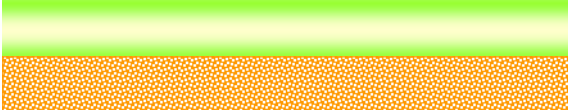
## Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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04 143 FR4 70 L36.105 P18

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

04\_143\_FR4\_700\_L36.105\_p18

Layers	in $\mu$	Material	Build-Up	Assembly
Layer-1	70 $\mu$	Copper	 (180 $\mu$ PrePreg-Type: 7628)	
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
Layer-2	105 $\mu$	Copper		
	360 $\mu$	L-FR4		
Layer-3	105 $\mu$	Copper		
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
Layer-99	70 $\mu$	Copper		

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